



## Product Change Notification - KSRA-21IPNN877

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**Date:**

30 Mar 2019

**Product Category:****Notification subject:**

CCB 3768 Final Notice: Implement Microchip Part Aging, Combination Rules, Recertification, and Label Policy for selected Microsemi products (Microsemi (LCLD, VPT, TIM and WIFI) products.

**Notification text:****PCN Status:**

Final notification

**PCN Type:**

Manufacturing Change

**Microchip Parts Affected:**

Please open the attachments found in the attachments field below labeled as PCN\_#\_Affected\_CPN.

Note 1: For your convenience Microchip includes identical files in two formats (.pdf and .xls).

Note 2: As part of the integration process additional products may be identified that were not part of the original list.

**Description of Change:**

Implement Microchip Part Aging, Combination Rules, Recertification Program, and Label Policy for selected Microsemi products within the Microsemi subsidiaries Microsemi Solutions Sdn. Bhd. which includes Voice Line Circuits and Line Drivers (LCLD), Audio and Voice (VPT), Timing and Synchronization (TIM) and WLAN FEM, PA and LNA's (WiFi) Business Units

Change in Part Aging Policy

Change in Combination Rules

Change in Program

Change in Reel/Bag/Inner/Outer Shipping/MSL Labels

**Pre Change:**

Using Microsemi's packing process.

**Post Change:**

Using Microchip's packing process.

**Pre and Post Change Summary:**

NOTE: See attached Packing Pre and Post Changes for the changes of the following.

Details		PRE CHANGE (MSCC)	POST CHANGE (Microchip)
Part Aging Policy	LCLD, VPT TIM:	Shelf life 5 years  Standard products over 24 months will require notification to the customer  Shipments of Low Volume products over 24 months will not require customer notification or a special Certificate of Conformance (C of C)	may ship parts up to 48 months (4 years).  For Microchip Direct and Sample is 5 years
	WIFI:	Can ship date codes up to 3 years after recertification.	

<b>Combination Rules</b>		1 device  <b>LCLD, VPT, and TIM:</b> 2 date codes per reel or bulk pack  <b>WIFI:</b> 2 trace codes  between date codes	1 device  3 date codes  No time limit between date codes
<b>Recertification Program</b>		<b>LCLD, VPT, and TIM:</b> Not  <b>WIFI:</b> Recertification of solderability at 3 years and solderability and electrical test at 5 years.  <b><i>Storage time per package:</i></b>  <b><u>Plastic Package:</u></b>  <b>Physical / Mechanical</b> - 3 years by D/C  <b>Electrical</b> - 5 years by D/C  <b><u>Hermetic Package:</u></b>  <b>Physical / Mechanical</b> - 3 years by D/C  <b>Electrical</b> - 3 years by D/C	Parts older than 24 months (2 years)  It may include one or more of the following: inspections, retest, rescanning and repacking of parts.
<b>Reel/Bag/Inner/Outer/Die/Wafer Sale Shipping Label</b>		Microsemi branded labels  without bar code  (see attachment for details)	Microchip branded labels  with 2D barcode  (see attachment for details)
<b>MSL Caution Label</b>	<b>Shelf Life</b>	12 months	24 months
	<b>MSL</b>	Specific Label per MSL Level	Common Label per MSL Level
	<b>Peak Package Body Temp</b>	Pre- Printed	To refer barcode label or filled up as applicable
	<b>Bag Seal Date</b>	Printed on MSL caution label	To refer barcode label or filled up as applicable

**Impacts to Data Sheet:**

None

**Change Impact:**

None

**Reason for Change:**

To improve productivity by standardizing the packing method as part of the integration of Microsemi



and Microchip.

### Change Implementation Status:

In Progress

### Earliest Implementation Date:

May 1, 2019

Note: The earliest implementation date is the earliest date that we may implement any combination of the changes listed in this PCN as we will not implement any of the proposed changes prior to this date. After the earliest implementation these changes may occur to any product over the course of many months depending on inventory levels and business conditions.

### Time Table Summary:

	March 2019						May 2019				
Workweek	09	10	11	12	13	📅 🗓️ 📅	18	19	20	21	22
Final PCN Issue Date					X						
Estimated Implementation Date							X				

### Method to Identify Change:

Traceability, label, inner and outer boxes.

### Contact Microchip:

You may contact your local [Microchip Sales and Distribution](#). Contact information is also provided on the attached Frequently Asked Questions (FAQ).

If applicable, please also copy your local Microchip field sales and/or field quality representative.

### Revision History:

**March 30, 2019:** Issued final notification.

The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable products.

### Attachment(s):

[Frequently Asked Questions Microsemi May 2019.pdf](#)

[LCLD WIFI VPT and TIM Packing Pre and Post Changes.pdf](#)

[PCN\\_KSRA-21IPNN877 Affected CPN.pdf](#)

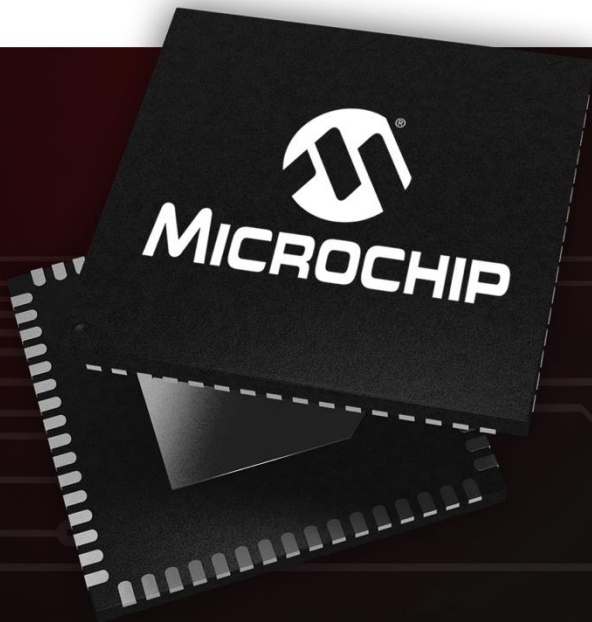
[PCN\\_KSRA-21IPNN877 Affected CPN.xlsx](#)

Please contact your local [Microchip sales office](#) with questions or concerns regarding this notification.

### Terms and Conditions:

If you wish to receive Microchip PCNs via email please register for our PCN email service at our [PCN home page](#) select register then fill in the required fields. You will find instructions about registering for Microchips PCN email service in the [PCN FAQ](#) section.

If you wish to change your PCN profile, including opt out, please go to the [PCN home page](#) select login and sign into your myMicrochip account. Select a profile option from the left navigation bar and make the applicable selections.



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Mixed-Signal, Analog & Flash-IP Solutions



***LCLD, WIFI, VPT, TIM– Packing Pre and Post Changes***



**MICROCHIP**

**Part Aging**

# Part Aging

PRE CHANGE	POST CHANGE
<p><u>LCLD, VPT, TIM:</u></p> <ul style="list-style-type: none"> <li>- Shippable finished goods inventory with date codes not to exceed an age of five years. Product exceeding five years of shelf life will be scrapped.</li> <li>- Shipments of Standard products with a date code over 24 months of age will require notification to the customer through the Microsemi Customer Care group.</li> <li>- Shipments of Low Volume products with a date code over 24 months of age will not require customer notification or a special Certificate of Conformance (C of C) (Refer#135817)</li> </ul> <p><u>WIFI:</u></p> <p>Can ship date codes up to 3 years after do recertification. Refer# SGQ1377</p>	<p>Microchip may ship parts up to <u>48 months (4 years)</u>.</p> <p>Reason: Material sets used to manufacture integrated circuits have shown no degradation in solderability, moisture sensitivity or reliability of products after 48 months.</p> <p><i>For more information related to Microchip's part aging strategy, please visit the following link on our website: <a href="#">Component Age Policy</a></i></p> <p>For Microchip Direct and Sample is 5 years</p>



**MICROCHIP**

**Combination Rule**

# Combination Rule- Tray, Tube and T&R

PRE CHANGE	POST CHANGE
<ul style="list-style-type: none"><li>▪ Only like MPN's are allowed to be combined.</li><li>▪ Up to <b>2</b> date codes per reel or bulk pack box.</li><li>▪ For WIFI: control to two trace codes only combined in a single reel (instead of two date codes)</li><li>▪ Up to a thirteen-week span (newest – oldest date code, YYWW) of assembly production is allowed for all packages.</li><li>▪ Do not combine lots from material with different assembly locations</li><li>▪ Do not combine lots from material with different wafer fabrication sites.</li></ul>	<ul style="list-style-type: none"><li>▪ 1 Device.</li><li>▪ 3 Date codes.</li><li>▪ No limit time span between D/C</li><li>▪ No limit to number of production lots follow date code combination rule.</li><li>▪ 1 Assembly Site.</li><li>▪ 1 Test Site.</li><li>▪ 1 Wire Material.</li><li>▪ 1 Wafer Fab</li><li>▪ No limit for Die Revision, Die ID, Fab Revision and test flow.</li></ul>





**MICROCHIP**

**Recertification Program**

# Recertification Program

PRE CHANGE	POST CHANGE
<p><b>LCLD, VPT, TIM : No define in 07-001</b></p> <p><b>WIFI:</b> Recertification of solderability at 3 years and solderability and electrical test at 5 years.</p> <p><b><i>Storage time per package:</i></b></p> <p><b><u>Plastic Package:</u></b></p> <p><b>Physical / Mechanical</b> – 3 years by D/C</p> <p><b>Electrical</b> – 5 years by D/C</p> <p><b><u>Hermetic Package:</u></b></p> <p><b>Physical / Mechanical</b> – 3 years by D/C</p> <p><b>Electrical</b> – 3 years by D/C</p>	<p>Parts older than 24 months (2 years) old will be recertified prior shipment. It may include one or more of the following: inspections, retest, rescanning and repacking of parts.</p>



**MICROCHIP**

**Bag/Inner carton Label  
(LCLD, VPT, and TIM)**

# Bag Label (LCLD, VPT, and TIM)

## PRE CHANGE

(1P) ORDERING P/N: ZL10060LDF1



(6P) MATERIAL ITEM: ZL10060LDF1.SA



(1T) LOT NO: 516LEEYS01



(9D) D/C: 0516



(Q) QTY: 1000



(9D) D/C:



(Q) QTY:



(9D) D/C:



(Q) QTY:



(Q) TOTAL: 1000



(4L) Country of Origin: PHILIPPINES



PKG BOM:



## POST CHANGE

(1P) CATALOG P/N: ABCDEFGHIJKL-BB-CC-DDDD-EEEE-FF



(1T) LOT NO.: 114601899000MTAI



MSL: 3/260 C  
PKG: TFBGA  
LEAD: 48



(Q) QTY  
2500

(P) CUST. P/N: ABCDEFGH IJKLMNOP QIRSTUV REV A



D/C	QTY
1407	250
1408	1000
1509	1250

MPC: ABCDEFGHKLMO



SEAL DATE: MMDDYY  
WAFER QTY: -  
WAFER REV: -  
RECERT D/C: -  
WAFER LOT: -

ID#:(001) TRACE CODE: 1407B1R,1408B1Q,1509A3R



MADE IN  
THAILAND

# Inner Carton Label (LCLD, VPT, and TIM)

## PRE CHANGE

MICROSEMI SEMICONDUCTOR

(1D) DRY PACK SEAL DATE: 16MAY14

(1P) ORDERING P/N: ZL50110GAG2

(1T) LOT NO: 419LETSS01

(Q) TOTAL QUANTITY: 120

(9D) DATE (TRACE) CODE: 1417GAA

(4L) COUNTRY OF ORIGIN: TAIWAN

(6P) MATERIAL ITEM: ZL50110GAG2

(3S) BOX ID: 419LETSS01052813432

PKG L/C : PBGA 552

PKG BOM

THIS LINE UP WITH BOX EDGE

MICROSEMI SEMICONDUCTOR

(K) CUST PO : 27915112

(P) CUST PN: 4330214

SHIP REQ: 0080412336000001

PRINTED BY: 19162 20140528

ZL50110GAG2

## POST CHANGE

(1P) CATALOG P/N: ABCDEFGHIJKL-BB-CC-DDDD-EEEE-FF

(1T) LOT NO.: 114601899000MTAI

(P) CUST. P/N: ABCDEFGH IJKLMNO PQRSTU REV A

MPC: ABCDEFGHJKLMNO

ID#: (001) TRACE CODE: 1407B1R.1408B1Q.1509A3R

SEAL DATE: MM/DD/YY

WAFER QTY: -

WAFER REV: -

RECERT D/C: -

WAFER LOT: -

MSL: 3/260 C

PKG: TFBGA

LEAD: 48

RoHS e3 e

(Q) QTY

2500

D/C QTY

1407 250

1408 1000

1509 1250

MADE IN THAILAND




**Reel/Bag/Inner carton Label  
(WIFI- Giga Solution, Sigurd,  
and ASEM)**

# Reel / Bag/ Inner carton Label (WIFI – Giga Solution and Sigurd)

## PRE CHANGE

Giga Solution

Pb-free/RoHS		<b>Microsemi</b> ANALOG MIXED SIGNAL GROUP
ASSY LOCATION: CARSEM, CHD-1A		
DEVICE: LX5540LL-TR		
LOT NO.: WH543P003-2		
QTY. BOX: 3000	DATE CODE: 0835A	
FINAL TEST: YES	BOX NO: 1 OF 5	
QA: 09/12/08		

Pb free		<b>Microsemi</b> ANALOG MIXED SIGNAL GROUP
ASSY LOCATION: Carsem Sigurd		
DEVICE: LX5518LQ -TR		
LOT NO.: BWH746P033		
QTY. BOX: 3000	DATECODE: 318A	
FINAL TEST: YES	BOX NO: OF:	
QA: Piolo		




## POST CHANGE

(1P) CATALOG P/N: ABCDEFGHIJKL-BB-CC-DDDD-EEEE-FF		
(1T) LOT NO.: 114601899000MTAI		MSL: 3/260 C PKG: TFBGA LEAD: 48
(P) CUST. P/N: ABCDEFGH IJKLMNO PQRSTUV REV A	(Q) QTY	2500
MPC: ABCDEFGHJKLMNO	D/C	QTY
SEAL DATE: MM/DD/YY	1407	250
WAFER QTY: -	1408	1000
WAFER REV: -	1509	1250
RECERT D/C: -		
WAFER LOT: -		
ID#:(001) TRACE CODE: 1407B1R,1408B1Q,1509A3R	MADE IN THAILAND	



# Reel / Bag/ Inner carton Label (WIFI – ASEM)

## PRE CHANGE

Reel/Bag

<b>PB FREE / RoHS</b>		 <b>Microsemi</b>	
ANALOG MIXED SIGNAL GROUP ASSY LOCATION : <b>CHINA</b>			
DEVICE : PD69108ILQ-TR			
			
LOT NO. : SL96175 / SL96176			
			
QTY : 1300 / 700		D/C : 1349M / 1349L	
FINAL TEST : YES		QA:	

Inner carton

<b>PB FREE / RoHS</b>		 <b>Microsemi</b>	
ANALOG MIXED SIGNAL GROUP ASSY LOCATION : <b>CHINA</b>			
DEVICE : PD69108ILQ-TR			
			
LOT NO. : SL96175 / SL96176			
			
QTY : 1300 / 700		D/C : 1349M / 1349L	
FINAL TEST : YES		QA:	
BOX ID : 340LG01S1C0011160052			
			

## POST CHANGE

(1P) CATALOG P/N: ABCDEFGHIJKL-BB-CC-DDDD-EEEE-FF			
			
(1T) LOT NO.: 114601899000MTAI		 <b>RoHS</b>  <b>E3</b>  <b>E</b>	
		MSL: 3/260 C PKG: TFBGA LEAD: 48	
(P) CUST. P/N: ABCDEFGH IJKLMNO PQRSTUV REV A		(Q) QTY <b>2500</b>	
			
MPC: ABCDEFGHKLMO		D/C QTY	
		1407 250	
SEAL DATE: MMDDYY		1408 1000	
WAFER QTY: -		1509 1250	
WAFER REV: -			
RECERT D/C: -			
WAFER LOT: -			
ID#: (001) TRACE CODE: 1407B1R, 1408B1Q, 1509A3R			
			
MADE IN THAILAND			














**MICROCHIP**

**Outer carton Label  
(LCLD, VPT, TIM)**

# Outer Carton Label (LCLD, VPT, and TIM)

## PRE CHANGE

 <p><b>Ship From:</b> Microsemi Semiconductor C/O ASE Electronics (M) S/B PH IV, Free Industrial Zone 11900 Penang MALAYSIA</p>	<p><b>Ship To:</b></p> <div style="border: 1px solid black; padding: 5px; width: 100px; height: 40px; margin: 0 auto;"> <p style="color: red; text-align: center;">Customer Ship To Address</p> </div>
<p>Description of Goods : INTEGRATED CIRCUITS</p>	
<p>(K) PURCHASE ORDER NUMBER: 27915112</p>	
	
<p>(P) CUSTOMER PART NUMBER: 4330214</p>	
	
<p>(1P) ORDERING P/N: ZL50110GAG2</p>	
	
<p>(Q) CARTON QUANTITY: 384</p>	
	
<p>SHIP REQ: 0080412336000001</p>	
	
<p>BOX ID: LE4050657F001</p>	
	
<p>SALES ORDER #: 0000218604</p>	
	
<p>FORWARDER: DHL AIR</p>	
<p>SHIP DATE: 16MAY14</p>	
<p>Country of Origin :TW</p>	<p>Package Count 1 OF 1</p>
	

## POST CHANGE

<p><b>SHIP TO:</b> PHILIPS CONSUMER ELECTRONICS WILSON LOGISTIC CT, 6/F PHILIPS IND BLDG., 24-28 KUNG KUNG YIP ST, KWAICHUNG HONG KONG</p>	
<p><b>B-HK-PHC-S2269812</b></p>	
	
<p>Cust. P/N: 3139 227 01992</p>	
	
<p>Catalog P/N: DSPIC33FJ128MC510T-I/PTC22</p>	<p>   </p>
	
<p>PO#: 55016400/2</p>	<p>SO #: 472542/26</p>
	<p>Qty: 200000</p>
	
	
<p>Hong Kong 10-21-2010 (mm-dd-yyyy)</p>	<p>Carton 1 of 20 19.5 kgs</p>
	




**Outer carton Label**  
**(WIFI- Giga Solution, Sigurd, ASEM)**

# Outer Carton Label (WIFI – Giga Solution)

## PRE CHANGE

Label 1

Pb-free/RoHS	 <b>Microsemi</b> ANALOG MIXED SIGNAL GROUP
ASSY LOCATION: CARSEM, CHINA	
DEVICE: LX5540LL-TR	
LOT NO: WH543P003-2	
QTY. BOX: 3000	DATE CODE: 0835A
FINAL TEST: YES	BOX NO: 1 OF 5
QA: 09/12/08	

Label 2

ZENITRON  
SSN1431357  
TAIWAN  
C/N 1 OF 2  
FROM TAIWAN  
N.W. KGS.  
G.W. KGS.

## POST CHANGE

SHIP TO: PHILIPS CONSUMER ELECTRONICS WILSON LOGISTIC CT, 6/F PHILIPS IND BLDG., 24-28 KUNG KUNG YIP ST, KWAICHUNG HONG KONG	
B-HK-PHC-S2269812 	
Cust. P/N: 3139 227 01992 	
Catalog P/N: DSPIC33FJ128MC510T-I/PTC22 	
PO#: 55016400/2 	SO #: 472542/26 
Qty: 200000 	
Hong Kong 10-21-2010 (mm-dd-yyyy)	
Carton 1 of 20 19.5 kgs	

# Outer Carton Label (WIFI – Sigurd)

## PRE CHANGE



## POST CHANGE

<b>B-HK-PHC-S2269812</b>		SHIP TO: PHILIPS CONSUMER ELECTRONICS WILSON LOGISTIC CT, 6/F PHILIPS IND BLDG., 24-28 KUNG KUNG YIP ST, KWAICHUNG HONG KONG	
Cust. P/N: 3139 227 01992			
Catalog P/N: DSPIC33FJ128MC510T-I/PTC22	   		
PO#: 55016400/2	SO #: 472542/26	Qty: 200000	
		Hong Kong 10-21-2010 (mm-dd-yyyy)	
		Carton 1 of 20 19.5 kgs	

# Outer Carton Label (WIFI – ASEM)

## PRE CHANGE

<b>Ship From :</b> ASE ELECTRONICS (M) SDN BHD, PHASE 4, FREE INDUSTRIAL ZONE 11900 BAYAN LEPAS PENANG.	<b>Ship To :</b> MENLO WORLDWIDE HK LTD UNIT 901, 9/F GRANDTECH CENTRE, NO 8 ON PING ST SID LEE YUEN, SHATIN NT. HONG KONG  ATTN : JAN LEE
<b>ASEM INVOICE NUMBER : LG9030031F</b> 	
<b>S/O # : 20190311</b> 	
<b>CUSTOMER PO NUMBER :</b> 	
<b>(P) CUSTOMER PART NO. :</b> 	
<b>DEVICE TYPE :PD69104ILQ – TR</b> 	
<b>(Q)CARTON QUANTITY : 2000</b> 	
<b>SHIPMENT NO. : 20190311</b> 	
<b>FORWARDER : DHL AIR</b>	<b>G/W : 1.62 KG</b>
<b>SHIP DATE : 11MAR19</b>	<b>N/W :1.28 KG</b>
<b>Country of Origin : TH</b>	<b>Package Count : 2 OF 2</b>
	

## POST CHANGE

<b>B-HK-PHC-S2269812</b> 		<b>SHIP TO:</b> PHILIPS CONSUMER ELECTRONICS WILSON LOGISTIC CT, 6/F PHILIPS IND BLDG., 24-28 KUNG KUNG YIP ST, KWAICHUNG HONG KONG
<b>Cust. P/N:</b> 3139 227 01992 		
<b>Catalog P/N:</b> DSPIC33FJ128MC510T-I/PTC22 		
<b>PO#:</b> 55016400/2 	<b>SO #:</b> 472542/26 	<b>Qty:</b> 200000 
	<b>Hong Kong</b> <b>10-21-2010</b> <b>(mm-dd-yyyy)</b>	<b>Carton 1</b> <b>of 20</b> <b>19.5 kgs</b>

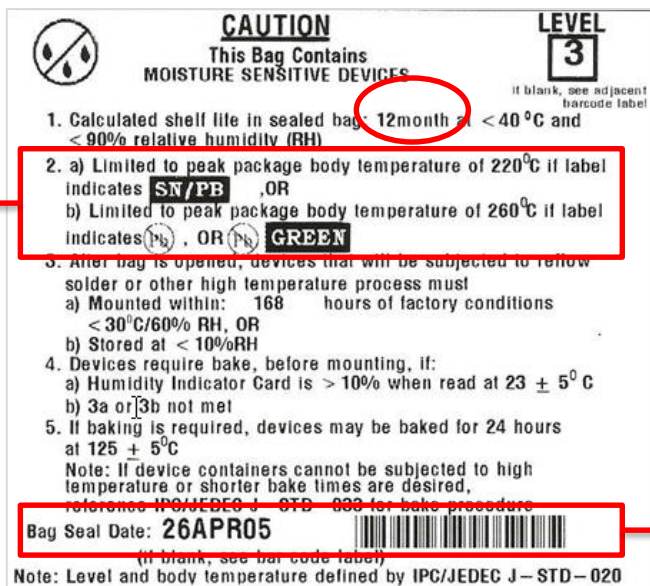


**MICROCHIP**

**MSL Caution Label**

# Outer Carton Label (WIFI – ASEM)

## PRE CHANGE



**CAUTION**  
This Bag Contains  
MOISTURE SENSITIVE DEVICES

**LEVEL 3**  
If blank, see adjacent barcode label

1. Calculated shelf life in sealed bag: 12month at < 40°C and < 90% relative humidity (RH)

2. a) Limited to peak package body temperature of 220°C if label indicates **SN/PB**, OR  
b) Limited to peak package body temperature of 260°C if label indicates **GREEN**

3. After bag is opened, devices that will be subjected to reflow solder or other high temperature process must  
a) Mounted within: 168 hours of factory conditions < 30°C/60% RH, OR  
b) Stored at < 10%RH

4. Devices require bake, before mounting, if:  
a) Humidity Indicator Card is > 10% when read at 23 ± 5°C  
b) 3a or 3b not met

5. If baking is required, devices may be baked for 24 hours at 125 ± 5°C  
Note: If device containers cannot be subjected to high temperature or shorter bake times are desired, reference IPC/JEDEC J-STD-033 for bake procedure

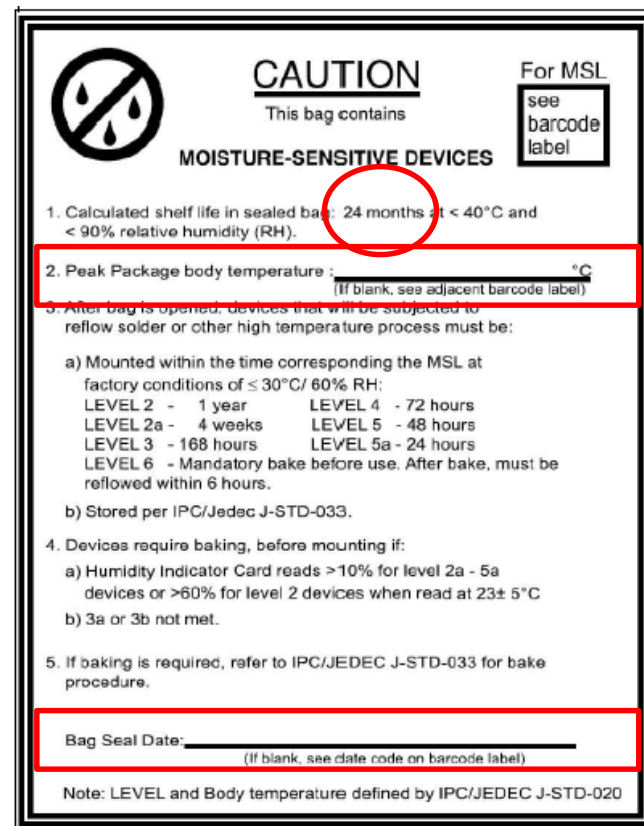
Bag Seal Date: **26APR05**  
(If blank, see bar code label)

Note: Level and body temperature defined by IPC/JEDEC J-STD-020

Pre printed peak package  
body temperature

Pre printed bag seal date

## POST CHANGE



**CAUTION**  
This bag contains  
MOISTURE-SENSITIVE DEVICES

**For MSL**  
see  
barcode  
label

1. Calculated shelf life in sealed bag: 24 months at < 40°C and < 90% relative humidity (RH)

2. Peak Package body temperature : \_\_\_\_\_ °C  
(If blank, see adjacent barcode label)

3. After bag is opened, devices that will be subjected to reflow solder or other high temperature process must be:  
a) Mounted within the time corresponding the MSL at factory conditions of ≤ 30°C/ 60% RH:  
LEVEL 2 - 1 year      LEVEL 4 - 72 hours  
LEVEL 2a - 4 weeks      LEVEL 5 - 48 hours  
LEVEL 3 - 168 hours      LEVEL 5a - 24 hours  
LEVEL 6 - Mandatory bake before use. After bake, must be reflowed within 6 hours.  
b) Stored per IPC/JEDEC J-STD-033.

4. Devices require baking, before mounting if:  
a) Humidity Indicator Card reads > 10% for level 2a - 5a devices or > 60% for level 2 devices when read at 23± 5°C  
b) 3a or 3b not met.

5. If baking is required, refer to IPC/JEDEC J-STD-033 for bake procedure.

Bag Seal Date: \_\_\_\_\_  
(If blank, see date code on barcode label)

Note: LEVEL and Body temperature defined by IPC/JEDEC J-STD-020



**END**

## Frequently Asked Questions (FAQ)

**Contacting Microchip:** Microchip has Sales Offices Worldwide. You have received this correspondence from a Microchip Inside Sales Representative, please continue to work with him/her to guide you through the transition. Should you need to find your local office, please visit our website at: [Microchip Sales and Distribution](#). Also note that your current Microsemi contacts have moved to the Microchip email system therefore their email address has changed to first name.last name@microchip.com

You may also contact the following individuals within your geography:

Americas: Rozita Yajadda ([Rozita.yajadda@microchip.com](mailto:Rozita.yajadda@microchip.com))

Europe: Renata Locatelli ([renata.locatelli@microchip.com](mailto:renata.locatelli@microchip.com))

APAC: Nora Lee ([nora.lee@microchip.com](mailto:nora.lee@microchip.com))

World Wide Distribution: Jennifer Innella ([jennifer.innella@microchip.com](mailto:jennifer.innella@microchip.com))

EMEA Distribution: Renata Locatelli ([renata.locatelli@microchip.com](mailto:renata.locatelli@microchip.com))

Asia Distribution: Derek Chan ([derek.chan@microchip.com](mailto:derek.chan@microchip.com))

**Open Direct Orders with Microsemi:** Open Orders for affected parts will be transferred to the Microchip Systems on or about May 1, 2019. Customers will be contacted by local sales offices prior to the transfer to ensure a smooth transition. All orders will be transferred in US\$ currency. The details of the currency conversion will be outlined by your local ISR contacts closer to the transfer date.

**MOQ:** Orders must be placed in multiples of tray, tube, bag, or reel size. Additionally, there may be a Purchase Order/Order Line minimum. Existing Microsemi orders being converted to Microchip orders will be subject to the Microchip base quantity multiples and Microchip Purchase Order/Order Line item minimum.

Should changes be required when migrating open backlog, each customer will be notified with full details by your local Inside Sales contact.

**Order Acknowledgement:** Microchip provides Acknowledgements for all new Direct orders entered and for each change made to an existing Direct order. This document is typically provided via email. Once an existing order is transferred from the Microsemi system to the Microchip system an Order Acknowledgement will then be sent. Customers or Distributors that have an EDI connection will receive either an 855 acknowledgement (US & Asia) or ORDRSP acknowledgement (Europe) via EDI.

**Cancel/Reschedule:** The table below provides information on the Microchip Cancel/Reschedule policy:

Catalog PN Restriction	Cancellation	CRD Push Out	CRD Pull In Allowed	CRD Push Out Allowed
Standard	>30 days PRD	>30 days PRD	Y	Y
Custom, Non Standard	>60 days PRD	>60 days PRD	Y	Y
QS9000	>60 days PRD	>60 days PRD	Y	Y
NCNR	N/A	N/A	Y	N

\*CRD – Customer Requested Delivery Date

\*PRD – Microchip Anticipated Delivery Date

**Advanced Ship Notice (ASN):** When placing a Direct Order with Microchip, customers can elect to receive an Advance Ship Notice. This document advises that your order is prepared to ship to the location identified on your Purchase Order. This option will be discussed with you by your local Microchip Contact prior to the go live date in May.

**Managing Product Requirements during the Transition:** The Microsemi order entry and shipments systems for items identified in this information packet will transition to Microchip systems on or about May 1, 2019. Until that time, please continue to manage your product requirements as you do today. If changes have been made with your local Representative Sales Office, please see the Microchip section **Contacting Microchip** from above. Microchip will have a ‘Quiet Period’ that will occur for several days surrounding the final integration so that we can import all existing Purchase Orders into our system. During that time, we will not Accept New Orders, Modify/Cancel Existing Orders, or Ship Product. Please contact your local sales office with any questions or concerns.

**Shipping and Invoicing after the transition:** After May 1, 2019, all products identified in this phase will be shipped and invoiced from Microchip. Please alert your **Receiving** and **Accounts Payable** departments of this change; in our experience, some clients must cancel existing backlog and then re-issue a new P.O. to Microchip. Over the coming weeks Microchip will contact you to discuss all your needs to insure there is no interruption in your supply chain.

**Vendor/Supplier Code:** If your system requires a new code to support order placement to Microchip and receive in Microchip shipments, please arrange as needed.

**Shipping Labels, Boxes and Packing Methods:** Labels, Boxes and Packing methods will be standardized to Microchip’s current processes. Special shipping labels for special

products such as programming products, special testing, etc. will adhere to the standard Microchip process over time. See attached Standard Microchip Label Specification.

**Lots, Trace Codes, Date Codes, Part Aging, and Shelf Life:** Standard Microchip methods for combining production lots, trace codes and date codes into tubes, trays, and reel media will apply as well as standard Microchip Part Aging and Shelf Life Policies. Microchip quality documents and policies including part aging policy are found on our website. [Quality Documents and Policies](#)

**Payment Terms:** Standard payment terms are N30

**Terms & Conditions:** Microchip Sales are subject to the company's Terms and Conditions ("T&C"). Microchip T&C does differ slightly depending on whether the customer is in the European Union or elsewhere in the world and whether they are purchasing Direct or through microchipDIRECT. Microchip Terms and Conditions are attached.

**Product/Process Change Notification (PCN) after the transition:** Shortly after May 1, 2019, the standard Microchip methods for notifying customers about product changes that include PCNs and End of Life (EOL) notices will begin to apply (please note that this process may integrate over multiple phases of select products over an extended period). Part of the standard method includes a PCN email service that we expect to be available to select Microsemi customer/product combinations soon after or on May 1, 2019. Once available, customers who wish to receive PCN's via email are expected to register for PCN email service on our PCN web page. Information about how and when to register will be provided in separate integration PCNs as the products you are interested in are phased in. The Microsemi PCN system will continue to be used in conjunction with a partial Microchip PCN system until the full Microchip PCN system can support Microsemi products soon after or on May 1, 2019 (review how in the Microsemi Integration PCN's below). The Microsemi PCN system will be terminated after the transition to Microchip systems is complete. Information about Microchip's PCN system can be found at this link: [Microchip PCN Website](#)

**Microsemi Integration PCN's:** Until full integration to Microchip's PCN system all PCN's related to the integration will be provided using the Microsemi PCN system and can also be found at this Microchip website: [Product Change Notifications](#). This same notification process will be used to inform customers when your select products will be targeted to be integrated and the timeline for those products. Additional integration PCNs for Microsemi products may be issued for the following changes; ordering part numbering convention, shipping labels, shipping boxes, packing methods, part aging/shelf life, top marking, manufacturing site, Bill of Material (BOM), Silicon, and EOL among others.

**RoHS Information:** Can be found on the Microchip Website under RoHS PB Free, RoHS Device Search. An email will be generated from the system with all of the pertinent information regarding the device search.

<http://www.microchip.com/wwwproducts/Rohs/>

RMES-21XNOX705 - CCB 3769 Final Notice: Implement Microchip top marking changes for selected Microsemi (LCLD, VPT, TIM and WIFI) products.

Affected Catalog Part Number (CPN)

PCN_KSRA-21IPNN877
CATALOG_PART_NBR
BCM6304KMLG
BCM6304KMLGT
BCM6305KMLG
BCM6305KMLGT
BCM65050IMLG
BCM65050IMLGT
BCM65060IMLG
BCM65060IMLGT
CLQ214029/KW/BP2N
CR3142
DS3100GN2
DS3100SWGN2
DS3102GN2
DS3104GN2
DS3105LN2
DS3106LN2
DS31400GN2
DS31400SWGN2
DS31404GN2
DS31406GN2
DS31407GN2
DS31408GN2
DS31408SWGN2
DS31415GN2
LE57D111BTC
LE57D111BTCT
LE57D121BTC
LE57D121BTCT
LE57D122BTC
LE57D122BTCT
LE58QL021BVC
LE58QL021BVCT
LE58QL021FJC
LE58QL021FJCT
LE58QL022BVC
LE58QL022BVCT
LE58QL02FJC
LE58QL02FJCT
LE58QL031DJC
LE58QL031DJCT
LE58QL061BVC
LE58QL061BVCT
LE58QL063HVC
LE58QL063HVCT

RMES-21XNOX705 - CCB 3769 Final Notice: Implement Microchip top marking changes for selected Microsemi (LCLD, VPT, TIM and WIFI) products.

Affected Catalog Part Number (CPN)

PCN_KSRA-21IPNN877
CATALOG_PART_NBR
LE79112AKVC
LE79112AKVCT
LE79114KVC
LE79124KVC
LE79124KVCT
LE79128KVC
LE79128KVCT
LE79234KVC
LE792388TVC
LE792388TVCT
LE792388VQC
LE792388VQCT
LE79252BTC
LE79252BTCT
LE79271AMQC
LE79271AMQCT
LE79271MQC
LE79271MQCT
LE79272PQC
LE79272PQCT
LE79Q2281DVC
LE79Q2281DVCT
LE79Q2284MVC
LE79Q2284MVCT
LE79R70-1DJC
LE79R70-1DJCT
LE79R70-1FQC
LE79R70DJC
LE79R70DJCT
LE79R79-1DJC
LE79R79-1DJCT
LE79R79-1FQC
LE79R79-2DJC
LE79R79-2DJCT
LE79R79-3DJC
LE79R79-3DJCT
LE87100NQC
LE87100NQCT
LE87251NQC
LE87251NQCT
LE87270NQC
LE87270NQC
LE87270NQCT
LE87270NQCT

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Affected Catalog Part Number (CPN)

PCN_KSRA-21IPNN877
CATALOG_PART_NBR
LE87281NQC
LE87281NQCT
LE87282MQC
LE87282MQCT
LE87285NQC
LE87285NQCT
LE87290YQC
LE87290YQCT
LE87401NQC
LE87401NQCT
LE87402MQC
LE87402MQCT
LE87411NQC
LE87411NQCT
LE87501NQC
LE87501NQCT
LE87502MQC
LE87502MQCT
LE87511NQC
LE87511NQCT
LE87536NQC
LE87536NQCT
LE87557NQC
LE87557NQCT
LE87611NQC
LE87611NQCT
LE87612MQC
LE87612MQCT
LE87614MQC
LE87614MQCT
LE88010BQC
LE88010BQCT
LE88101DVC
LE88102KQC
LE88131BLC
LE88131BLCT
LE88221DLC
LE88221DLCT
LE88231DLC
LE88231DLCT
LE88241DLC
LE88241DLC
LE88241DLCT
LE88262TQC



RMES-21XNOX705 - CCB 3769 Final Notice: Implement Microchip top marking changes for selected Microsemi (LCLD, VPT, TIM and WIFI) products.

Affected Catalog Part Number (CPN)

PCN_KSRA-21IPNN877
CATALOG_PART_NBR
LE88262TQCT
LE88266DLC
LE88266DLCT
LE88266TQC
LE88266TQCT
LE88276DLC
LE88276DLCT
LE88286DLC
LE88286DLCT
LE88286TQC
LE88286TQCT
LE88506DVC
LE88506DVCT
LE88830KQC
LE88830KQCT
LE89010QVC
LE89010QVCT
LE89116QVC
LE89116QVCT
LE89156PQC
LE89156PQCT
LE89316QVC
LE89316QVCT
LE89810BSC
LE89810BSCT
LE89900AMC
LE89900AMCT
LE9530CETC
LE9530CETCT
LE9530CPQC
LE9530CPQCT
LE9530DETC
LE9530DETCT
LE9530DPQC
LE9530DPQCT
LE9540CUQC
LE9540CUQC
LE9540CUQCT
LE9540CUQCT
LE9540DUQC
LE9540DUQC
LE9540DUQCT
LE9540DUQCT
LE9541CUQC

RMES-21XNOX705 - CCB 3769 Final Notice: Implement Microchip top marking changes for selected Microsemi (LCLD, VPT, TIM and WIFI) products.

Affected Catalog Part Number (CPN)

PCN_KSRA-21IPNN877
CATALOG_PART_NBR
LE9541CUQCT
LE9541DUQC
LE9541DUQCT
LE9551CMQC
LE9551CMQCT
LE9551DMQC
LE9551DMQCT
LE9621AQC
LE9621AQCT
LE9622RQC
LE9622RQCT
LE9632RQC
LE9632RQCT
LE9641PQC
LE9641PQCT
LE9642PQC
LE9642PQCT
LE9643AQC
LE9643AQCT
LE9651PQC
LE9651PQCT
LE9652PQC
LE9652PQCT
LE9653AQC
LE9653AQCT
LE9661WQC
LE9661WQCT
LE9662WQC
LE9662WQCT
LE9672WQC
LE9672WQCT
LX5511LQ
LX5511LQ-TR
LX5518LQ
LX5518LQ-TR
LX5530LQ
LX5530LQ-TR
LX5531LQ
LX5531LQ-TR
LX5533LQ
LX5533LQ-TR
LX5535LQ
LX5535LQ-TR
LX5535LQ-TR-13122

RMES-21XNOX705 - CCB 3769 Final Notice: Implement Microchip top marking changes for selected Microsemi (LCLD, VPT, TIM and WIFI) products.

Affected Catalog Part Number (CPN)

PCN_KSRA-21IPNN877
CATALOG_PART_NBR
LX5551LQ
LX5551LQ-TR
LX5561LL
LX5561LL-TR
LX5563LL-TR
LX5575LL
LX5575LL-TR
LX5584BLQ
LX5584BLQ-TR
LX5584HLQ
LX5584HLQ-TR
LX5586ALL
LX5586ALL-TR
LX5586HLL
LX5586HLL-TR
LX5586LL
LX5586LL-TR
LX5589ALQ
LX5589ALQ-TR
LX5589BLQ
LX5589BLQ-TR
LX5589HLQ
LX5589HLQ-TR
LX5591LQ
LX5591LQ-TR
LX5602LQ
LX5602LQ-TR
MAX24188ETK2
MAX24188ETK2T
MAX24205EXG2
MAX24210EXG2
MAX24287ETK2
MAX24287ETK2T
MAX24288ETK2
MAX24288ETK2T
MAX24305EXG2
MAX24310EXG2
MAX24405EXG2
MAX24410EXG2
MAX24505EXG2
MAX24505EXG2003G
MAX24510EXG2
MAX24510EXG2Q00P
MAX24510EXG2Q00Q

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Affected Catalog Part Number (CPN)

PCN_KSRA-21IPNN877
CATALOG_PART_NBR
MAX24605EXG2
MAX24610EXG2
MAX24705EXG2
MAX24710EXG2
MAX3612ETM2
MAX3612ETM2T
MAX3624AETJ2
MAX3624AETJ2T
MAX3624UTJ2
MAX3624UTJ2T
MAX3625ACUG2
MAX3625ACUG2T
MAX3637ETM2
MAX3637ETM2T
MAX3638ETM2
MAX3638ETM2T
MAX3639ETM2
MAX3639ETM2T
MAX3670ETJ2
MAX3670ETJ2T
MAX3671ETN2
MAX3671ETN2T
MAX3674ECM2
MAX3674ECM2T
MAX3677CTJ2
MAX3677CTJ2T
MAX3678UTN2
MAX3678UTN2T
MAX3679AETJ2
MAX3679AETJ2T
MAX3697AETJ2
MAX3697AETJ2T
MAX3697CTJ2
MAX3697CTJ2T
MAX3698CTJ2
MAX3698CTJ2T
MAX9451EHJ2
MAX9451EHJ2T
MAX9452EHJ2
MAX9452EHJ2T
MT093AE1
MT093AP1
MT093APR1
MT8806AP1

RMES-21XNOX705 - CCB 3769 Final Notice: Implement Microchip top marking changes for selected Microsemi (LCLD, VPT, TIM and WIFI) products.

Affected Catalog Part Number (CPN)

PCN_KSRA-21IPNN877
CATALOG_PART_NBR
MT8806APR1
MT8808AP1
MT8808APR1
MT8809AP1
MT8809APR1
MT8812AE1
MT8812AP1
MT8812APR1
MT8815AE1
MT8815AP1
MT8816AE1
MT8816AF1
MT8816AP1
MT8816APR1
MT8870DN1
MT8870DNR1
MT8870DS1
MT8870DSR1
MT8880CN1
MT8880CP1
MT8880CPR1
MT8880CS1
MT8880CSR1
MT8888CN1
MT8888CP1
MT8888CS1
MT8888CSR1
MT8889CN1
MT8889CS1
MT8889CSR1
MT88E39AS1
MT88E39ASR1
MT88E43BS1
MT88E43BSR1
MT88L70AN1
MT88L70ANR1
MT88L70AS1
MT88L70ASR1
MT8952BP1
MT8952BPR1
MT8952BS1
MT8980DE1
MT8980DP1
MT8980DPR1

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Affected Catalog Part Number (CPN)

PCN_KSRA-21IPNN877
CATALOG_PART_NBR
MT8981DP1
MT8985AP1
MT8986AE1
MT8986AL1
MT8986AP1
MT8986APR1
MT89L80AP1
MT89L80APR1
MT89L85AP1
MT89L86AP1
MT9041BP1
MT9041BPR1
MT9042CP1
MT9074AL1
MT9074AP1
MT9074APR1
MT9075BL1
MT9075BP1
MT9076BB1
MT9076BP1
MT90812AL1
MT90812AP1
MT90823AB1
MT90823AL1
MT90826AL1
MT90866AG2
MT90869AG2
MT90871AV2
MT9122AP1
MT9123AP1
MT9123APR1
MT9126AS1
MT9126ASR1
MT9171AN1
MT9171ANR1
MT9171AP1
MT9171APR1
MT9172AN1
MT9172ANR1
MT9172AP1
MT9172APR1
MT9173AN1
MT9173ANR1
MT9174AN1

Affected Catalog Part Number (CPN)

PCN_KSRA-21IPNN877
CATALOG_PART_NBR
MVT209018/CX/GP2N
ZL30100QDG1
ZL30101QDG1
ZL30102QDG1
ZL30105QDG1
ZL30106QDG1
ZL30107GGG2
ZL30108LDG1
ZL30109QDG1
ZL30110LDF1
ZL30110LDG1
ZL30111QDG1
ZL30112LDG1
ZL30113LDF1
ZL30113LDG1
ZL30116GGG2V2
ZL30117GGG2
ZL30119GGG2
ZL30120GGG2
ZL30121GGG2V2
ZL30122GGG2
ZL30123GGG2
ZL30130GGG2
ZL30131GGG2
ZL30132GGG2
ZL30136GGG2
ZL30138GGG2
ZL30142GGG2
ZL30143GGG2
ZL30145GGG2
ZL30146GGG2
ZL30150GGG2
ZL30151LDF1
ZL30151LDG1
ZL30151LDG1Q01C
ZL30152GGG2
ZL30153GGG2
ZL30154GGG2
ZL30155GGG2
ZL30156GGG2
ZL30157GGG2
ZL30158GGG2
ZL30159GGG2
ZL30160GGG2

RMES-21XNOX705 - CCB 3769 Final Notice: Implement Microchip top marking changes for selected Microsemi (LCLD, VPT, TIM and WIFI) products.

Affected Catalog Part Number (CPN)

PCN_KSRA-21IPNN877
CATALOG_PART_NBR
ZL30161GDG2
ZL30162GDG2
ZL30163GDG2
ZL30164GDG2
ZL30164GDG2Q036
ZL30164GDG2Q03M
ZL30165GDG2
ZL30166GDG2
ZL30167GDG2
ZL30168GDG2
ZL30169LDF1
ZL30169LDG1
ZL30169LDG1Q00K
ZL30169LDG1Q00L
ZL30169LDG1Q00R
ZL30169LDG1
ZL30169LDG1Q01T
ZL30174LDG6
ZL30182LFF7
ZL30182LFG7
ZL30230GGG2
ZL30236GGG2
ZL30237GGG2
ZL30244LFF7
ZL30244LFG7
ZL30245LFF7
ZL30245LFG7
ZL30250LDF1
ZL30250LDG1
ZL30251LDF1
ZL30251LDF1Q00N
ZL30251LDF1Q00Y
ZL30251LDF1Q02W
ZL30251LDG1
ZL30251LDG1Q001
ZL30251LDG1Q002
ZL30251LDG1Q003
ZL30251LDG1Q009
ZL30251LDG1Q00F
ZL30251LDG1Q00G
ZL30251LDG1Q00M
ZL30251LDG1Q00N
ZL30251LDG1Q00S
ZL30251LDG1Q00Y



Affected Catalog Part Number (CPN)

PCN_KSRA-21IPNN877
CATALOG_PART_NBR
ZL30251LDG1Q013
ZL30251LDG1Q019
ZL30251LDG1Q01H
ZL30251LDG1Q01P
ZL30251LDG1Q01Z
ZL30251LDG1Q023
ZL30251LDG1Q024
ZL30251LDG1Q027
ZL30251LDG1Q02W
ZL30251LDG1Q03D
ZL30251LDG1Q03F
ZL30251LDG1Q03F
ZL30251LDG1Q03G
ZL30251LDG1Q03R
ZL30252LDF1
ZL30252LDG1
ZL30253LDF1
ZL30253LDF1Q02G
ZL30253LDG1
ZL30253LDG1Q01B
ZL30253LDG1Q01J
ZL30253LDG1Q01V
ZL30253LDG1Q01Y
ZL30253LDG1Q02G
ZL30253LDG1Q02M
ZL30253LDG1Q03J
ZL30253LDG1Q03L
ZL30253LDG1Q03N
ZL30254LDF1
ZL30254LDG1
ZL30255LFF7
ZL30255LFG7
ZL30255LFG7Q00W
ZL30256LFG7
ZL30260LDF1
ZL30260LDG1
ZL30261LDF1
ZL30261LDG1
ZL30261LDG1Q025
ZL30261LDG1Q02Y
ZL30262LDF1
ZL30262LDG1
ZL30263LDF1
ZL30263LDG1

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Affected Catalog Part Number (CPN)

PCN_KSRA-21IPNN877
CATALOG_PART_NBR
ZL30263LDG1Q01F
ZL30263LDG1Q038
ZL30263LDG1Q03B
ZL30263LDG1Q047
ZL30264LDF1
ZL30264LDG1
ZL30265LDF1
ZL30265LDG1
ZL30265LDG1Q01G
ZL30265LDG1Q033
ZL30265LDG1Q03V
ZL30265LDG1Q040
ZL30265LDG1Q048
ZL30266LDF1
ZL30266LDG1
ZL30267LDF1
ZL30267LDG1
ZL30267LDG1Q018
ZL30267LDG1Q030
ZL30267LDG1Q03C
ZL30267LDG1Q03W
ZL30267LDG1Q03Z
ZL30267LDG1Q042
ZL30267LDG1Q049
ZL30281LDF1
ZL30281LDG1
ZL30282LDF1
ZL30282LDG1
ZL30300GAG2
ZL30310GKG2
ZL30312GKG2
ZL30314GKG2
ZL30316GKG2
ZL30320GKG2
ZL30321GGG2
ZL30321GKG2
ZL30342GGG2
ZL30343GGG2
ZL30347GGG2
ZL30361GDG2
ZL30362GDG2
ZL30363GDG2
ZL30363GDG20041
ZL30363GDG2Q026

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Affected Catalog Part Number (CPN)

PCN_KSRA-21IPNN877
CATALOG_PART_NBR
ZL30363GDG2Q03H
ZL30364GDG2
ZL30364GDG20042
ZL30365GDG2
ZL30367GDG2
ZL30601LDG6
ZL30602LDG6
ZL30603LDG6
ZL30604LDG6
ZL30611LDG6
ZL30612LDG6
ZL30614LDF6
ZL30614LDG6
ZL30621LFF7
ZL30621LFG7
ZL30622LDF1
ZL30622LDG1
ZL30623LFF7
ZL30623LFG7
ZL30671LFG7
ZL30672LFG7
ZL30673LFG7
ZL30681LFG7
ZL30682LFG7
ZL30683LFG7
ZL30683LFG7Q04B
ZL30701LDG6
ZL30702LDF6
ZL30702LDG6
ZL30702LDG6Q02V
ZL30703LDG6
ZL30704LDF6
ZL30704LDG6
ZL30721LFF7
ZL30721LFG7
ZL30721LFG7Q022
ZL30721LFG7Q02K
ZL30722LDF1
ZL30722LDG1
ZL30722LDG1Q020
ZL30722LDG1Q021
ZL30723LFF7
ZL30723LFF7Q01N
ZL30723LFG7

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Affected Catalog Part Number (CPN)

PCN_KSRA-21IPNN877
CATALOG_PART_NBR
ZL30723LFG7Q00Z
ZL30723LFG7Q011
ZL30723LFG7Q01N
ZL30753LDG6
ZL30771LFG7
ZL30772LFG7
ZL30772LFG7Q04J
ZL30773LFG7
ZL38002QDG1
ZL38003GMG2
ZL38004GGG2
ZL38004QCG1
ZL38005QCG1
ZL38010DCE1
ZL38010DCF1
ZL38012LDF1
ZL38012LDG1
ZL38015QCG1
ZL38040LDF1
ZL38040LDG1
ZL38042LDF1
ZL38042LDG1
ZL38050LDF1
ZL38050LDG1
ZL38050UGB2
ZL38051LDF1
ZL38051LDG1
ZL38051UGB2
ZL38052LDF1
ZL38052LDG1
ZL38052UGB2
ZL38060LDF1
ZL38060LDG1
ZL38062LDF1
ZL38062LDG1
ZL38062UGB2
ZL38063LDF1
ZL38063LDG1
ZL38063UGB2
ZL38065QCG1
ZL38067LDF1
ZL38067LDG1
ZL38067UGB2
ZL38080LDF1

Affected Catalog Part Number (CPN)

PCN_KSRA-21IPNN877
CATALOG_PART_NBR
ZL38080LDG1
ZL38090LDF1
ZL38090LDG1
ZL38090UGB2
ZL38AMBLDF1
ZL38AMBLDG1
ZL38AMBUGB2
ZL40200LDF1
ZL40200LDG1
ZL40201LDF1
ZL40201LDG1
ZL40202LDF1
ZL40202LDG1
ZL40203LDF1
ZL40203LDG1
ZL40204LDF1
ZL40204LDG1
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ZL40217LDG1
ZL40218LDF1

Affected Catalog Part Number (CPN)

PCN_KSRA-21IPNN877
CATALOG_PART_NBR
ZL40218LDG1
ZL40219LDF1
ZL40219LDG1
ZL40220LDF1
ZL40220LDG1
ZL40221LDF1
ZL40221LDG1
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ZL40253LDF1
ZL40253LDG1
ZL40255LDF1
ZL40255LDG1
ZL40260LDF1
ZL40260LDG1
ZL40260QGF1

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Affected Catalog Part Number (CPN)

PCN_KSRA-21IPNN877
CATALOG_PART_NBR
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ZL40292LDG1
ZL50000DE1
ZL50000DP1
ZL50002AP1
ZL50010GDG2
ZL50010QCG1
ZL50011GDG2
ZL50011QCG1
ZL50012GDG2
ZL50012QCG1
ZL50015GAG2
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ZL50016GAG2
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ZL50023GAG2
ZL50023QCG1
ZL50031QEG1
ZL50064QCG1
ZL50075GAG2
ZL50110GAG2
ZL50111GAG2
ZL50112GAG2
ZL50114GAG2
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ZL50117GAG2
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ZL50233QCG1
ZL50234QCG1
ZL50235QCG1
ZL79124GDG2
ZL792388GDG2
ZL792588GDG2
ZL80001QAA1
ZL80001QAB1

RMES-21XNOX705 - CCB 3769 Final Notice: Implement Microchip top marking changes for selected Microsemi (LCLD, VPT, TIM and WIFI) products.

Affected Catalog Part Number (CPN)

PCN_KSRA-21IPNN877
CATALOG_PART_NBR
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ZL80002QAB1
ZL80007GAG2
ZL80018GGG2
ZL80020GDG2
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ZL80026LDF1
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ZL80027LDF1
ZL80027LDG1
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ZL80029LDG6
ZL80035LFG7
ZL80062LFG7
ZL80143GGG2
ZL81000GGG2
ZL88103LDF1
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ZL88105LDF1
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ZL88107LDF1
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ZL88601LDF1
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ZL88801LDF1
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ZLJ6080UAH